



bestirpower

BCW120N80M1

N-Channel Silicon Carbide Power MOSFET

1200 V, 30 A, 80mΩ

Features

- High switching speed with a low gate charge
- Fast intrinsic diode with low reverse recovery
- Robust Avalanche Capability
- 100% Avalanche Tested
- Pb-free, Halogen Free, and RoHS Compliant

$BV_{DSS,T_c=25^\circ C}$	$I_{D,T_c=25^\circ C}$	$R_{DS(on),typ}$	$Q_{g,typ}$
1200 V	30 A	80 mΩ	50 nC

Benefits

- System efficiency improvement
- Higher frequency applicability
- Increased power density
- Reduced cooling effort

Applications

- Solar inverter
- EV charging station
- UPS
- Industrial power supply



Absolute Maximum Ratings ($T_J = 25^\circ C$ unless otherwise noted)

Symbol	Parameter		Value	Unit
V_{DSS}	Drain to Source Voltage		1200	V
V_{GS}	Gate to Source Voltage(DC)		-10 / +22	V
V_{GSop}	Recommended Operation Value		-5 / +18	V
I_D	Drain Current	$V_{GS} = 18 V, (T_c = 25^\circ C)$	30	A
		$V_{GS} = 18 V, (T_c = 100^\circ C)$	21	
I_{DM}	Drain Current	Pulsed (Note1)	80	A
P_D	Power Dissipation	$(T_c = 25^\circ C)$	150	W
		Derate Above $25^\circ C$	1.00	W/ $^\circ C$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to 175	$^\circ C$
T_L	Maximum Lead Temperature for Soldering, 1/8" from Case for 10 Seconds		260	$^\circ C$

※Note 1 : Limited by maximum junction temperature.

Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	1	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	
T_{sold}	Soldering temperature, wave soldering only allowed at leads	260	$^\circ C$

BCW120N80M1

1200V 80mΩ Silicon Carbide Power MOSFET

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Off Characteristics						
BV_{DSS}	Drain to Source Breakdown Voltage	$V_{\text{GS}} = 0 \text{ V}, I_D = 1 \text{ mA}$	1200	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 1200 \text{ V}, V_{\text{GS}} = 0 \text{ V}$	-	1	100	μA
		$V_{\text{DS}} = 1200 \text{ V}, V_{\text{GS}} = 0 \text{ V}, T_J = 175^\circ\text{C}$	-	5	-	
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}} = +22 \text{ V}, V_{\text{DS}} = 0 \text{ V}$	-	-	+100	nA
		$V_{\text{GS}} = -10 \text{ V}, V_{\text{DS}} = 0 \text{ V}$	-	-	-100	

On Characteristics

$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}} = V_{\text{DS}}, I_D = 5.0 \text{ mA}$ (tested after $V_{\text{GS}} = 22 \text{ V}, 1 \text{ ms pulse}$)	2.0	3.0	4.5	V
$R_{\text{DS(on)}}$	Static Drain to Source On Resistance	$V_{\text{GS}} = 18 \text{ V}, I_D = 15 \text{ A}$	-	80	110	$\text{m}\Omega$
		$V_{\text{GS}} = 18 \text{ V}, I_D = 15 \text{ A}, T_J = 175^\circ\text{C}$	-	128	-	
g_{fs}	Transconductance	$V_{\text{DS}} = 20 \text{ V}, I_D = 15 \text{ A}$	-	11.4	-	S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{\text{DS}} = 800 \text{ V}, V_{\text{GS}} = 0 \text{ V}, f = 250 \text{ kHz}$	-	885	-	pF
C_{oss}	Output Capacitance		-	65	-	
C_{rss}	Reverse Capacitance		-	5	-	
E_{oss}	Stored Energy in Output Capacitance	$V_{\text{DS}} = 0 \text{ V} \text{ to } 800 \text{ V}, V_{\text{GS}} = 0 \text{ V}$	-	26	-	μJ
$C_{\text{o(er)}}$	Energy Related Output Capacitance		-	81	-	
$C_{\text{o(tr)}}$	Time Related Output Capacitance		-	142	-	
$Q_{\text{g(tot)}}$	Total Gate Charge	$V_{\text{DS}} = 800 \text{ V}, I_D = 15 \text{ A}, V_{\text{GS}} = -5 \text{ V} / 18 \text{ V}, \text{Inductive load}$	-	50	-	nC
Q_{gs}	Gate to Source Charge		-	13	-	
Q_{gd}	Gate to Drain "Miller" Charge		-	17	-	
R_G	Internal Gate Resistance	$f = 1 \text{ MHz}$ open drain	-	4.0	-	Ω

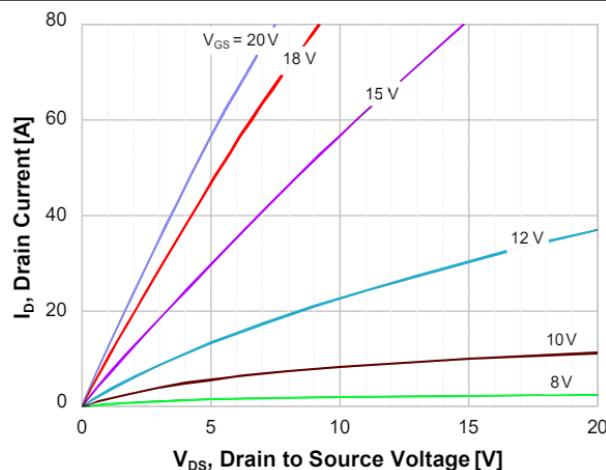
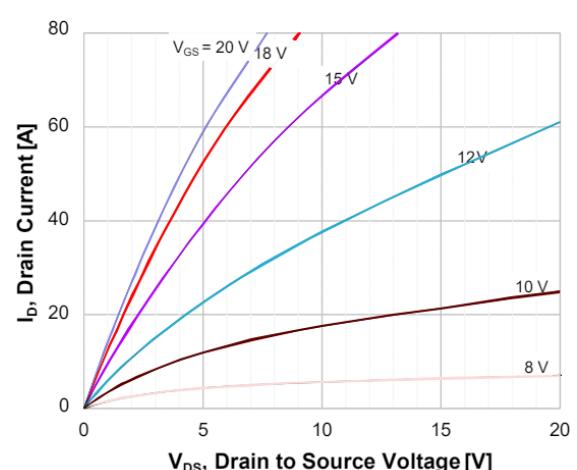
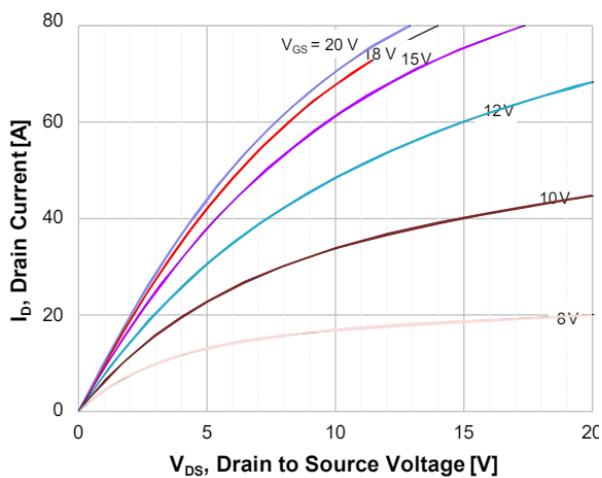
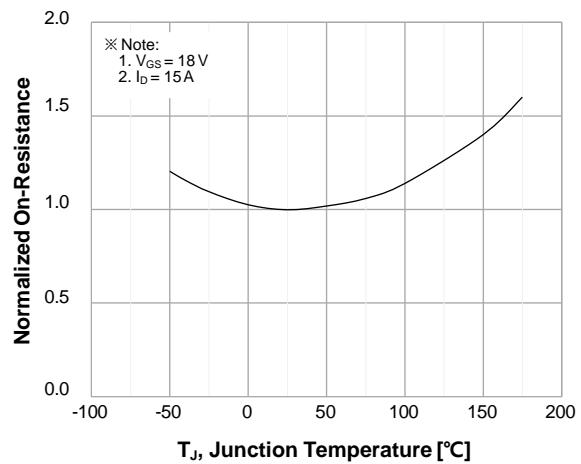
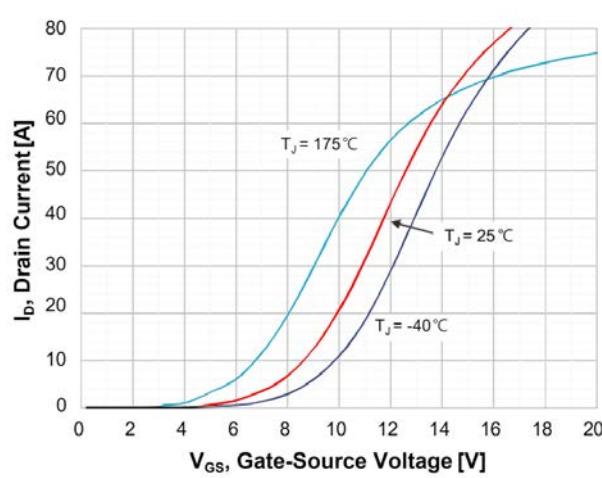
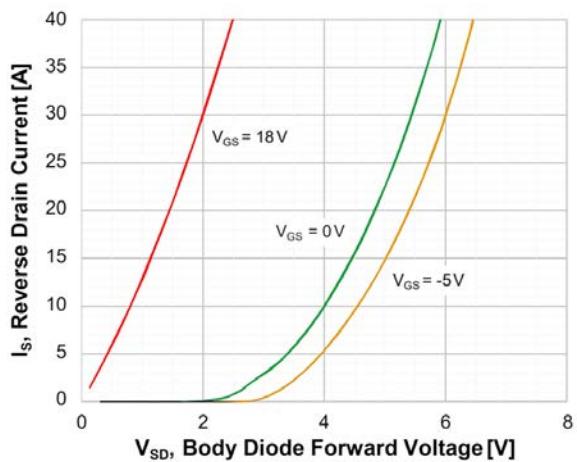
Switching Characteristics

$t_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DS}} = 800 \text{ V}, I_D = 15 \text{ A}, V_{\text{GS}} = -5 \text{ V} / 18 \text{ V}, R_G = 2 \Omega, \text{FWD : BCH120S010D1, Inductive load}$	-	14	-	ns
t_r	Turn-On Rise Time		-	21	-	
$t_{\text{d(off)}}$	Turn-Off Delay Time		-	24	-	
t_f	Turn-Off Fall Time		-	9	-	
E_{on}	Turn-on Switching Energy		-	183	-	
E_{off}	Turn-off Switching Energy		-	42	-	
E_{tot}	Total Switching Energy		-	225	-	

Source-Drain Diode Characteristics

I_S	Maximum Continuous Diode Forward Current	-	-	30	A
I_{SM}	Maximum Pulsed Diode Forward Current	-	-	80	
V_{SD}	Diode Forward Voltage	$V_{\text{GS}} = -5 \text{ V}, I_{\text{SD}} = 15 \text{ A}$	-	4.1	V
t_{rr}	Reverse Recovery Time		-	34	
Q_{rr}	Reverse Recovery Charge	$V_{\text{DD}} = 800 \text{ V}, I_{\text{SD}} = 15 \text{ A}, dI/dt = 3000 \text{ A}/\mu\text{s}, \text{Includes } Q_{\text{oss}}$	-	112	nC
			-	-	

Typical Performance Characteristics

Figure 1. On-Region Characteristics $T_J = -40^\circ\text{C}$

Figure 2. On-Region Characteristics $T_J = 25^\circ\text{C}$

Figure 3. On-Region Characteristics $T_J = 175^\circ\text{C}$

Figure 4. Normalized On-Resistance Characteristics vs. Temperature

Figure 5. Transfer Characteristics

Figure 6. Diode Forward Voltage Characteristics vs. Source-Drain Current $T_J = -40^\circ\text{C}$


Typical Performance Characteristics

Figure 7. Diode Forward Voltage Characteristics vs. Source-Drain Current $T_J = 25^\circ\text{C}$

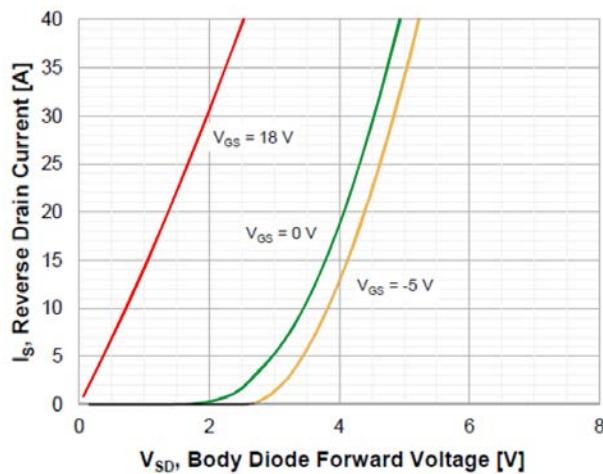


Figure 8. Diode Forward Voltage Characteristics vs. Source-Drain Current $T_J = 175^\circ\text{C}$

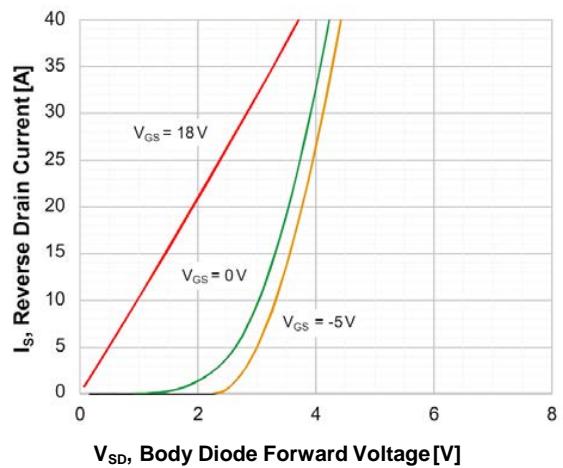


Figure 9. Threshold Voltage vs. Temperature

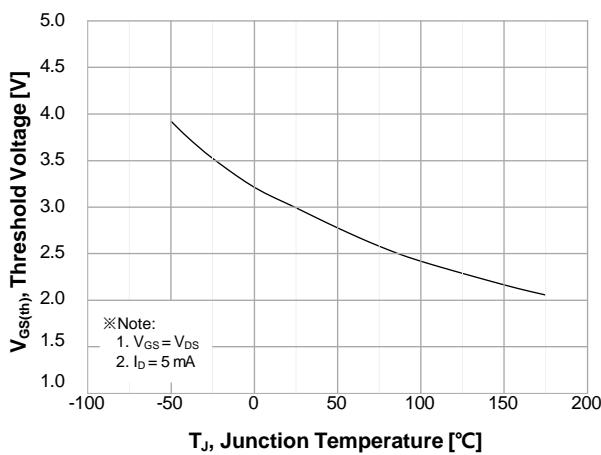


Figure 10. Gate Charge Characteristics

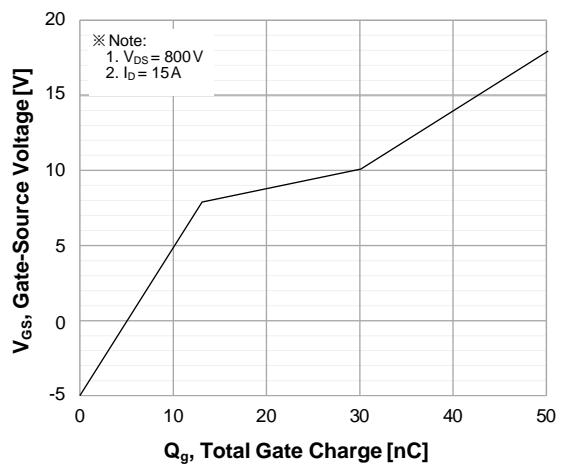


Figure 11. Stored Energy in Output Capacitance

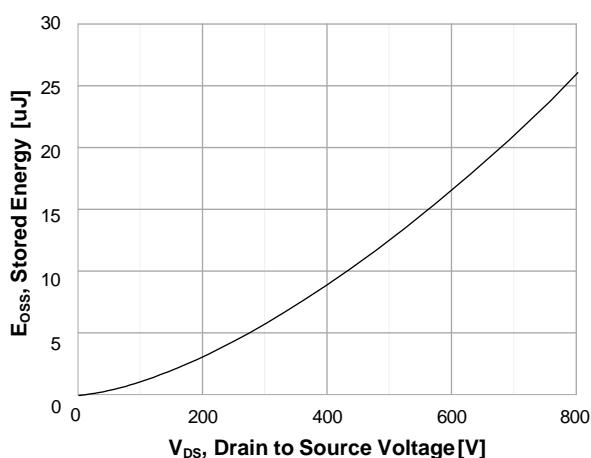
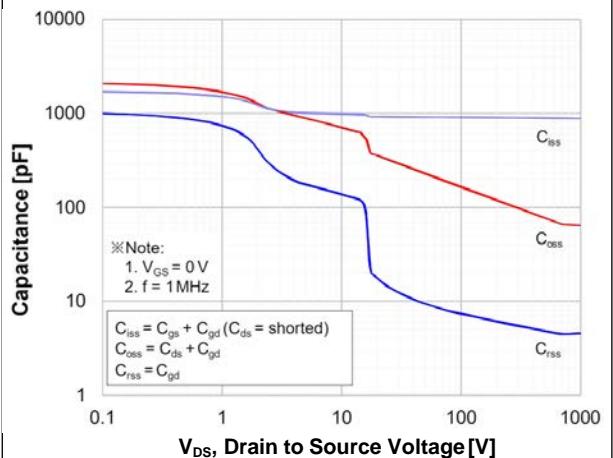


Figure 12. Capacitance Characteristics



Typical Performance Characteristics

Figure 13. Continuous Drain Current Derating vs. Case Temperature

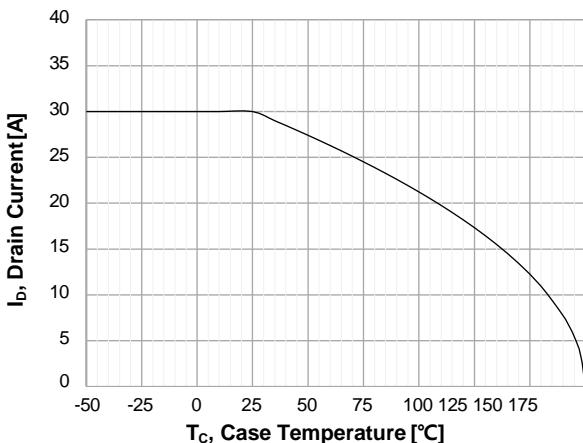


Figure 14. Maximum Power Dissipation Derating vs. Case Temperature

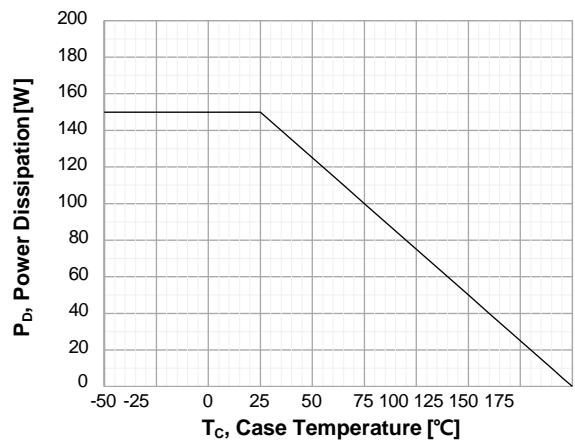


Figure 15. Typ. Switching losses vs. Drain current

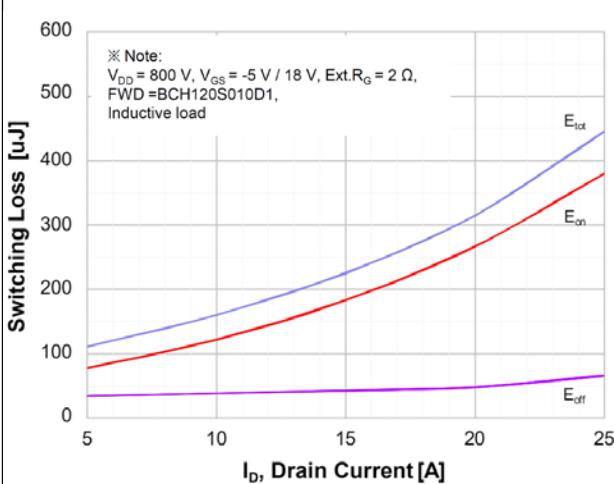


Figure 16. Typ. Switching losses vs. Gate resistance

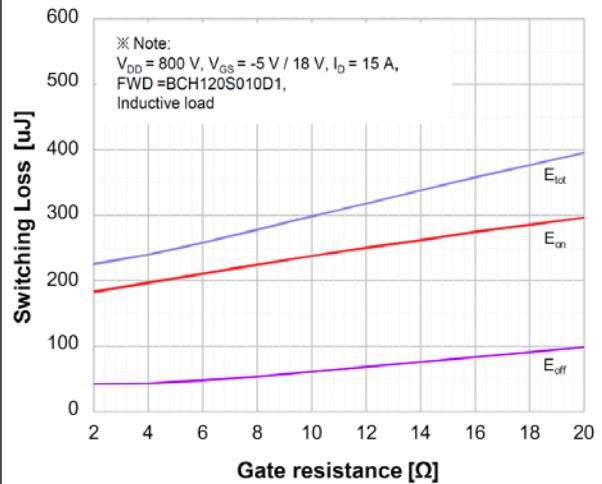


Figure 17. Typ. Switching losses vs. Drain current

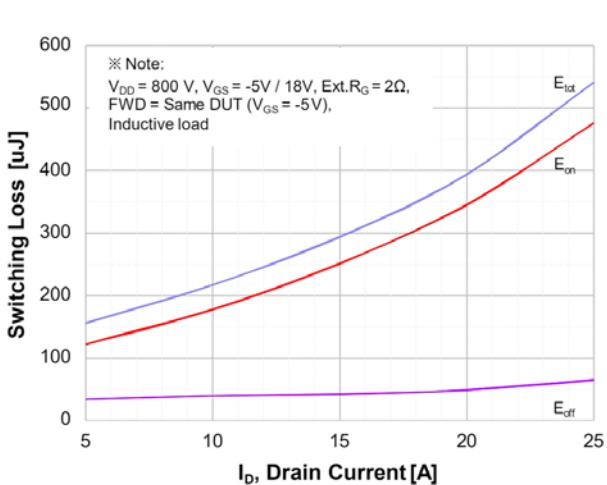
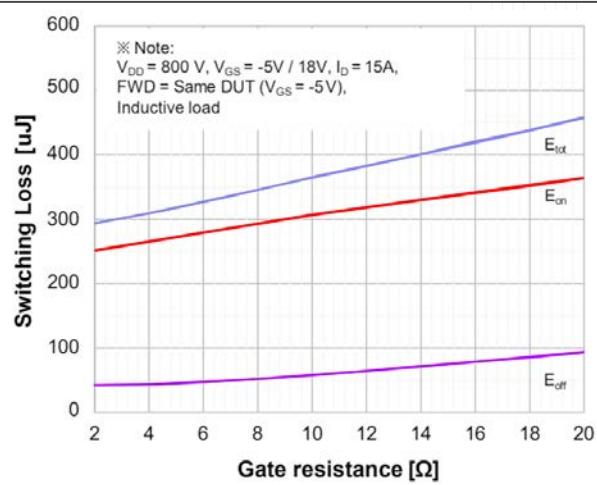


Figure 18. Typ. Switching losses vs. Gate resistance



Typical Performance Characteristics

Figure 19. Maximum Safe Operating Area

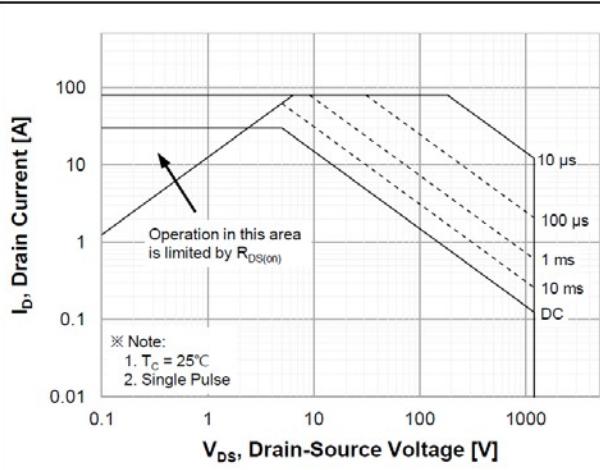


Figure 20. Transient Thermal Response Curve

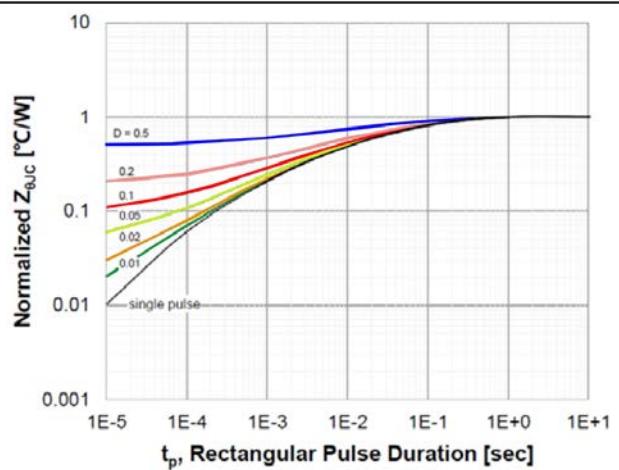


Figure 21. Inductive Load Switching Test Circuit and Waveforms

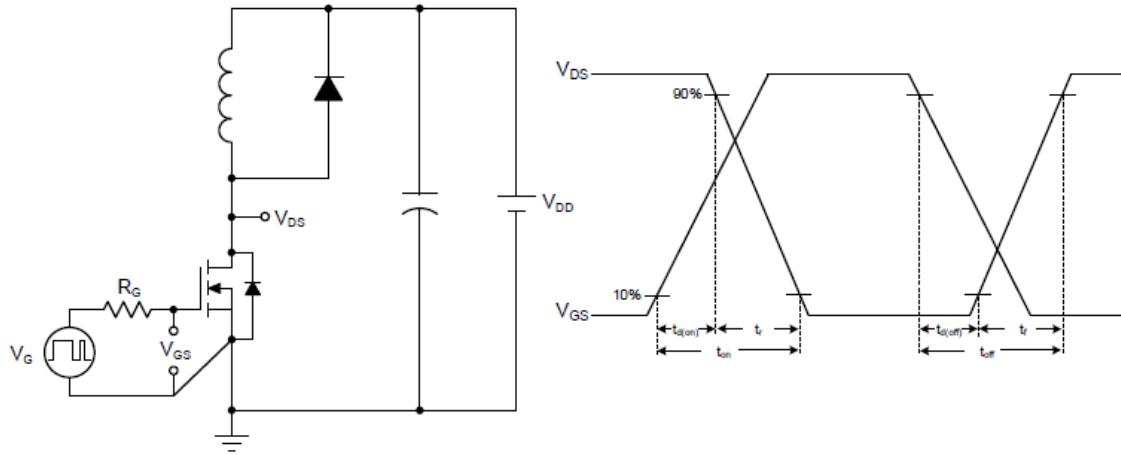
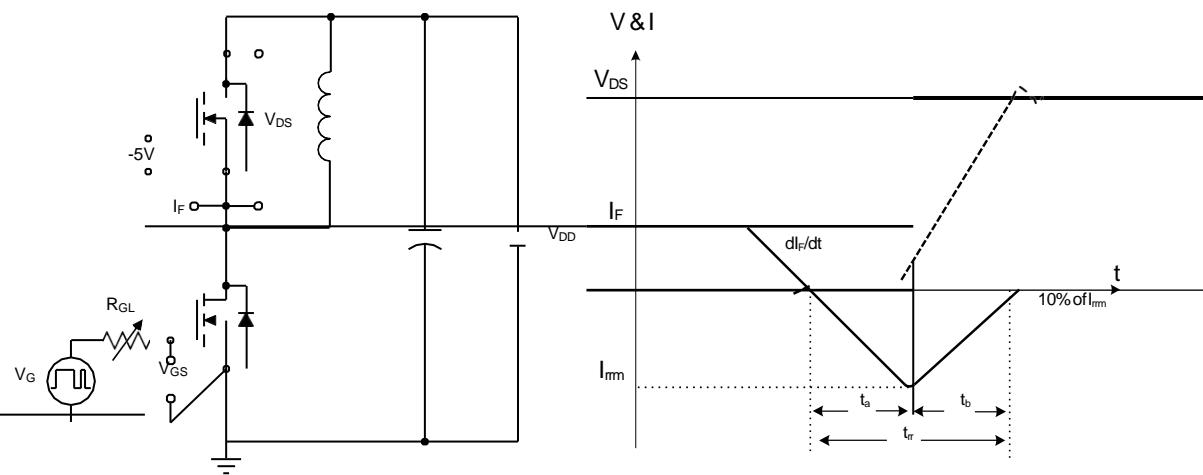
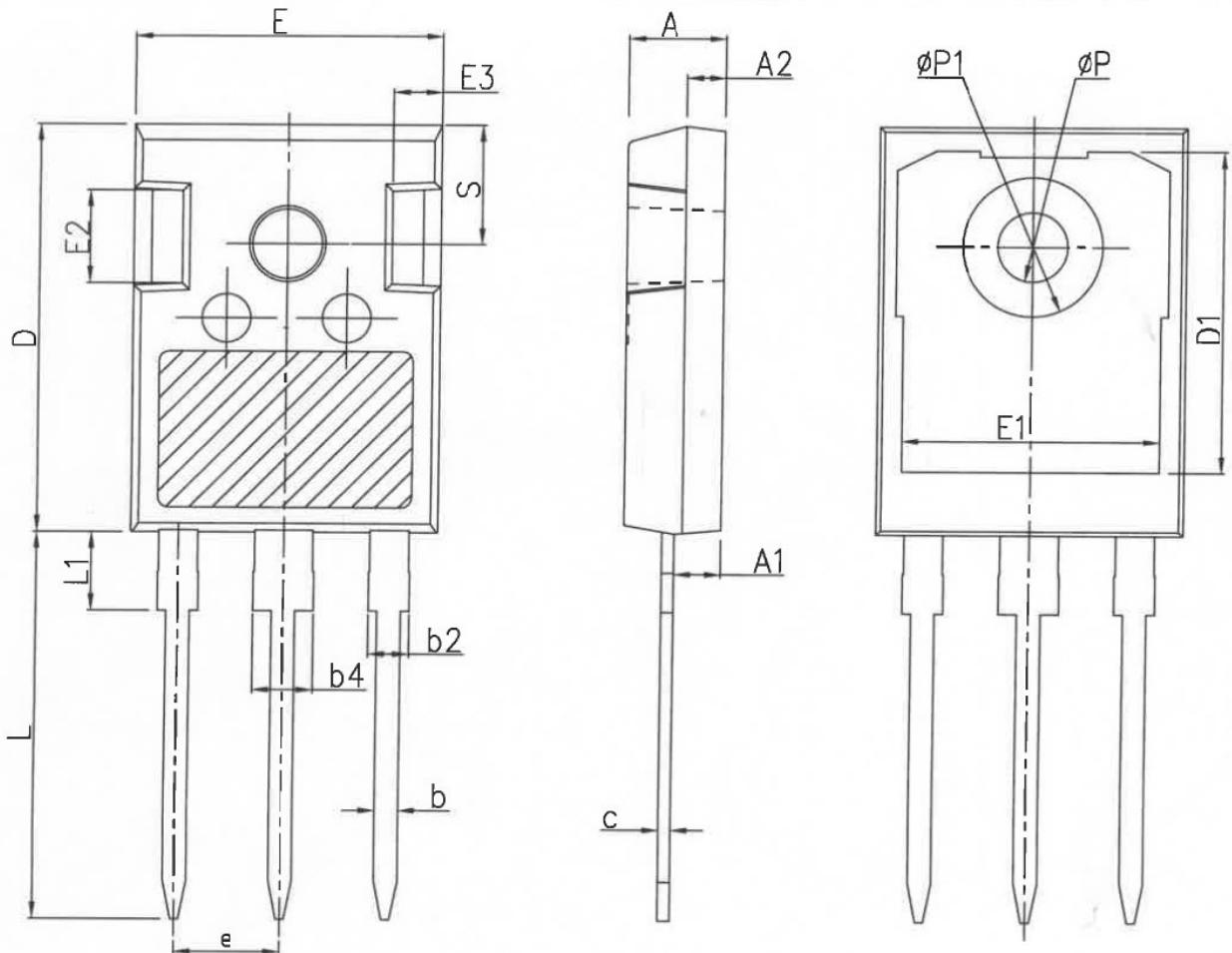


Figure 22. Peak Diode Recovery dv/dt Test Circuit and Waveforms



Package Outlines

TO247-3



COMMON DIMENSIONS

SYMBOL	mm		
	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.21	2.41	2.59
A2	1.85	2.00	2.15
b	1.11	1.21	1.36
b2	1.91	2.01	2.21
b4	2.91	3.01	3.21
c	0.51	0.61	0.75
D	20.70	21.00	21.30
D1	16.25	16.55	16.85
E	15.50	15.80	16.10
E1	13.00	13.30	13.60
E2	4.80	5.00	5.20
E3	2.30	2.50	2.70
e	5.44BSC		
L	19.62	19.92	20.22
L1	—	—	4.30
ΦP	3.40	3.60	3.80
ΦP1	—	—	7.30
S	6.15BSC		

* Dimensions in millimeters

Package Marking and Ordering Information

Part Number	Top Marking	Package	Packing Method	Quantity
BCW120N80M1	BCW120N80M1	TO247-3	Tube	30 units

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